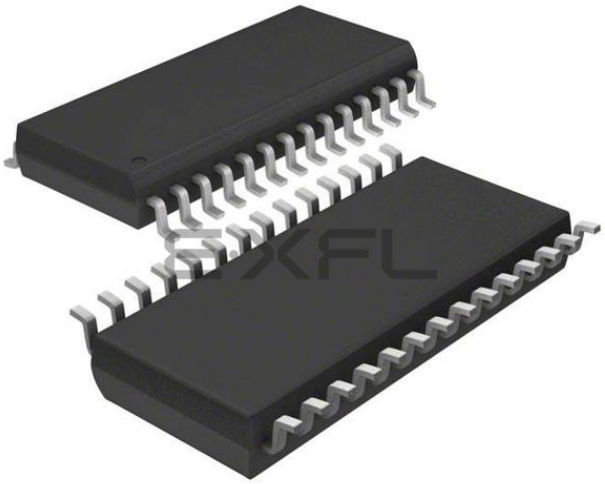

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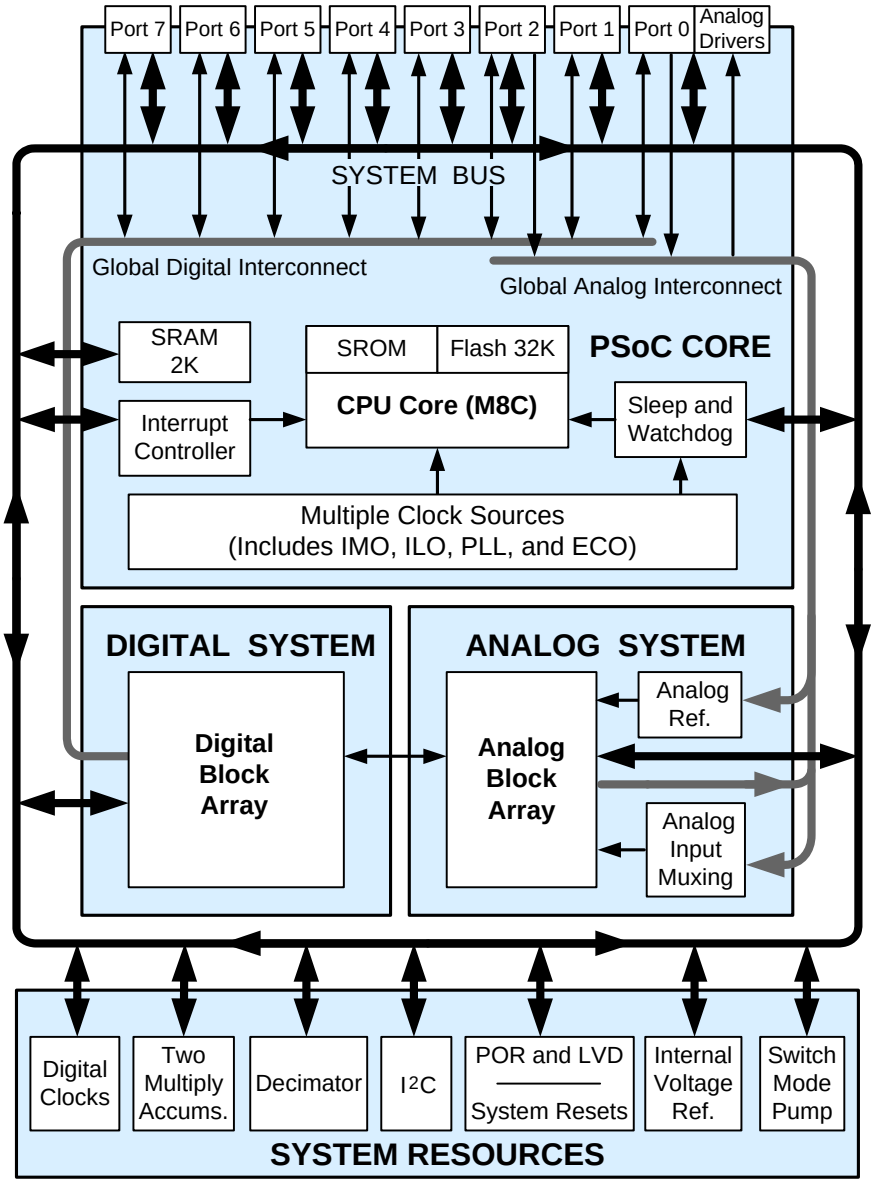
What Are Embedded - Microcontrollers - Application Specific?

Application-specific microcontrollers are engineered to

Details	
Product Status	Obsolete
Applications	HB LED Controller
Core Processor	M8C
Program Memory Type	FLASH (32KB)
Controller Series	CY8CLED
RAM Size	2K x 8
Interface	I²C, SPI, UART/USART
Number of I/O	24
Voltage - Supply	3V ~ 5.25V
Operating Temperature	-40°C ~ 85°C
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8cled16-28pvxit

Logic Block Diagram



EZ-Color™ Functional Overview

Cypress's EZ-Color family of devices offers the ideal control solution for High Brightness LED applications requiring intelligent dimming control. EZ-Color devices combine the power and flexibility of Programmable System-on-Chip (PSoC); with Cypress's precise illumination signal modulation (PrISM) modulation technology providing lighting designers a fully customizable and integrated lighting solution platform.

The EZ-Color family supports a range of independent LED channels from 4 channels at 32 bits of resolution each, up to 16 channels at 8 bits of resolution each. This enables lighting designers the flexibility to choose the LED array size and color quality. PSoC Designer software, with lighting specific drivers, can significantly cut development time and simplify implementation of fixed color points through temperature, optical, and LED binning compensation. EZ-Color's virtually limitless analog and digital customization allow for simple integration of features in addition to intelligent lighting, such as Battery Charging, Image Stabilization, and Motor Control during the development process. These features, along with Cypress' best-in-class quality and design support, make EZ-Color the ideal choice for intelligent HB LED control applications.

Target Applications

- LCD Backlight
- Large Signs
- General Lighting
- Architectural Lighting
- Camera/Cell Phone flash
- flashlights

The PSoC Core

The PSoC core is a powerful engine that supports a rich feature set. The core includes a central processing unit (CPU), memory, clocks, and configurable general purpose I/O (GPIO).

The M8C CPU core is a powerful processor with speeds up to 48 MHz, providing a four million instructions per second (MIPS) 8-bit Harvard-architecture microprocessor. The CPU utilizes an interrupt controller with 25 vectors, to simplify programming of real time embedded events. Program execution is timed and protected using the included Sleep and watchdog timers (WDT).

Memory encompasses 32 KB of flash for program storage, 2 KB of SRAM for data storage, and up to 2 KB of EEPROM emulated using the flash. Program flash utilizes four protection levels on blocks of 64 bytes, allowing customized software IP protection.

The EZ-Color family incorporates flexible internal clock generators, including a 24 MHz internal main oscillator (IMO) accurate to 2.5% over temperature and voltage. The 24 MHz IMO can also be doubled to 48 MHz for use by the digital system. A low power 32 kHz internal low speed oscillator (ILO) is provided for the Sleep timer and WDT. If crystal accuracy is desired, the 32.768 kHz external crystal oscillator (ECO) is available for use as a real time clock (RTC) and can optionally generate a crystal-accurate 24 MHz system clock using a PLL. The clocks, together with programmable clock dividers (as a System Resource), provide the flexibility to integrate almost any timing requirement into the EZ-Color device.

EZ-Color GPIOs provide connection to the CPU, digital and analog resources of the device. Each pin's drive mode may be selected from eight options, allowing great flexibility in external interfacing. Every pin also has the capability to generate a system interrupt on high level, low level, and change from last read.

The Digital System

The digital system is composed of 16 digital PSoC blocks. Each block is an 8-bit resource that can be used alone or combined with other blocks to form 8, 16, 24, and 32-bit peripherals, which are called user modules. Digital peripheral configurations include those listed below.

- PrISM (8-to 32-bit)
- PWMs (8-to 32-bit)
- PWMs with Dead band (8-to 32-bit)
- Counters (8-to 32-bit)
- Timers (8-to 32-bit)
- UART 8 bit with selectable parity (up to 4)
- SPI master and slave (up to 4 each)
- I^2C slave and multi-master (1 available as a System Resource)
- Cyclical Redundancy Checker/Generator (8- to 32-bit)
- IrDA (up to 4)
- Generators (8-to 32-bit)

The digital blocks can be connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by EZ-Color device family. This allows you the optimum choice of system resources for your application. Family resources are shown in Table 1 on page 6.

Register Reference

Register Conventions

Abbreviations Used

The register conventions specific to this section are listed in the following table.

Convention	Description
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
C	Clearable register or bit(s)
#	Access is bit specific

Register Mapping Tables

This chapter lists the registers of the CY8CLED16 EZ-Color device.

The device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks, Bank 0 and bank 1. The XOI bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XOI bit is set the user is in Bank 1.

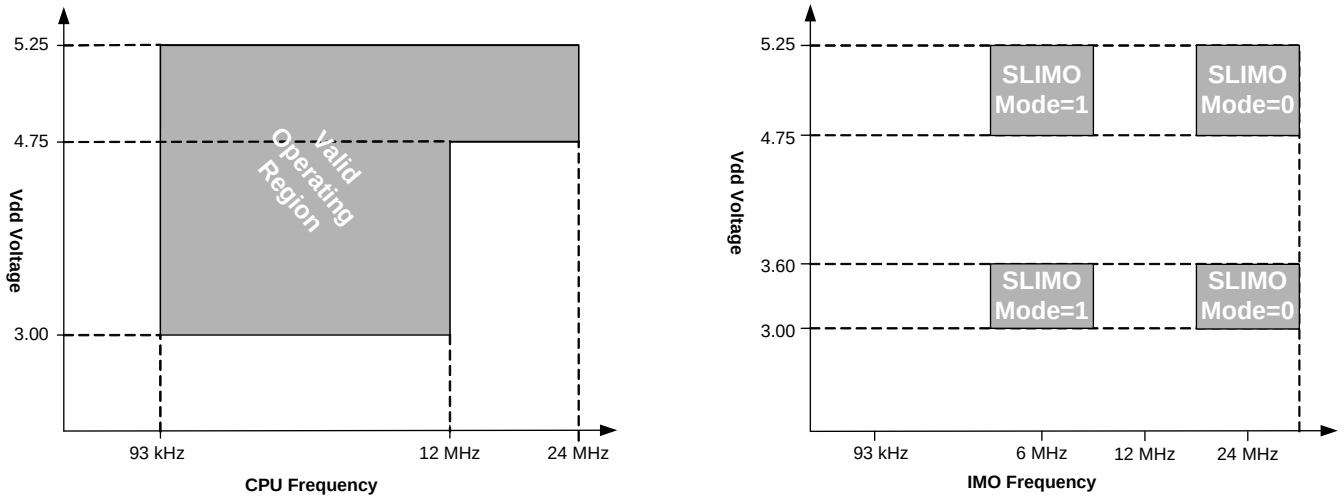
Note In the following register mapping tables, blank fields are reserved and should not be accessed.

Electrical Specifications

This section presents the DC and AC electrical specifications of the CY8CLED16 EZ-Color device. For the most up-to-date electrical specifications, confirm that you have the most recent data sheet by going to the web at http://www.cypress.com.

Specifications are valid for –40 °C ≤ T_A ≤ 85 °C and T_J ≤ 100 °C, except where noted. Refer to Table 20 for the electrical specifications for the internal main oscillator (IMO) using SLIMO mode.

Figure 5. Voltage versus CPU Frequency, and IMO Frequency Trim Options



DC GPIO Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and -40 °C ≤ T_A ≤ 85°C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 7. DC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{PU}	Pull-up Resistor	4	5.6	8	kΩ	
R_{PD}	Pull-down Resistor	4	5.6	8	kΩ	
V_{OH}	High output level	V_{DD} - 1.0	–	–	V	IOH = 10 mA, V_{DD} = 4.75 to 5.25 V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). 80 mA maximum combined IOH budget.
V_{OL}	Low output level	–	–	0.75	V	IOL = 25 mA, V_{DD} = 4.75 to 5.25 V (8 total loads, 4 on even port pins (for example, P0[2], P1[4]), 4 on odd port pins (for example, P0[3], P1[5])). 150 mA maximum combined IOL budget.
I_{OH}	High level source current	10	–	–	mA	VOH = V_{DD}-1.0 V. See the limitations of the total current in the Note for VOH.
I_{OL}	Low level sink current	25	–	–	mA	VOL = 0.75 V. See the limitations of the total current in the Note for VOL.
V_{IL}	Input low level	–	–	0.8	V	V_{DD} = 3.0 to 5.25.
V_{IH}	Input high level	2.1	–		V	V_{DD} = 3.0 to 5.25.
V_H	Input hysterisis	–	60	–	mV	
I_{IL}	Input leakage (Absolute Value)	–	1	–	nA	Gross tested to 1 μA.
C_{IN}	Capacitive load on pins as input	–	3.5	10	pF	Package and pin dependent. Temp = 25 °C.
C_{OUT}	Capacitive load on pins as output	–	3.5	10	pF	Package and pin dependent. Temp =25 °C.

DC Operational Amplifier Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and -40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

The operational amplifier is a component of both the Analog Continuous Time PSoC blocks and the analog switched capacitor PSoC blocks. The guaranteed specifications are measured in the Analog Continuous Time PSoC block. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 8. 5-V DC Operational Amplifier Specifications

Symbol	Description	Min	Typ	Max	Unit	Notes
V_{OSOA}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = Medium, Opamp bias = Low Power = Medium, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	 – – – – – –	 1.6 1.6 1.6 1.6 1.6 1.6	 10 10 10 10 10 10	 mV mV mV mV mV mV	–
TCV_{OSOA}	Average input offset voltage drift	–	4	23	µV/°C	
I_{EBOA}	Input leakage current (port 0 analog pins)	–	200	–	pA	Gross tested to 1 µA
C_{INOA}	Input capacitance (port 0 analog pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
V_{CMOA}	Common mode voltage range (All cases, except Power = High, Opamp bias = High) Common mode voltage range (Power = High, Opamp bias = High)	0 0.5	– –	V_{DD} V_{DD} – 0.5	V V	The common-mode input voltage range is measured through an analog output buffer. The specification includes the limitations imposed by the characteristics of the analog output buffer.
CMRROA	Common mode rejection ratio	60	–	–	dB	–
GOLOA	Open loop gain	80	–	–	dB	–
$V_{OHIGHOA}$	High output voltage swing (internal signals)	V_{DD} – 0.01	–	–	V	–
V_{OLOWOA}	Low output voltage swing (internal signals)	–	–	0.1	V	–
I_{SOA}	Supply current (including associated AGND buffer) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = Medium, Opamp bias = Low Power = Medium, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	 – – – – – –	 150 300 600 1200 2400 4600	 200 400 800 1600 3200 6400	 µA µA µA µA µA µA	–
$PSRR_{OA}$	Supply voltage rejection ratio	67	80	–	dB	$V_{SS} \le V_{IN} \le (V_{DD} – 2.25)$ or $(V_{DD} – 1.25\ V) \le V_{IN} \le V_{DD}$.

Table 9. 3.3-V DC Operational Amplifier Specifications

Symbol	Description	Min	Typ	Max	Unit	Notes
V_{OSOA}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = Medium, Opamp bias = Low Power = Medium, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	 – – – – – –	 1.4 1.4 1.4 1.4 1.4 –	 10 10 10 10 10 –	 mV mV mV mV mV mV	Power = High, Opamp bias = High setting is not allowed for 3.3 V V_{DD} operation.
TCV_{OSOA}	Average input offset voltage drift	–	7	40	µV/°C	–
I_{EBOA}	Input leakage current (port 0 analog pins)	–	200	–	pA	Gross tested to 1 µA.
C_{INOA}	Input capacitance (port 0 analog pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C
V_{CMOA}	Common mode voltage range	0	–	V_{DD}	V	The common-mode input voltage range is measured through an analog output buffer. The specification includes the limitations imposed by the characteristics of the analog output buffer.
$CMRR_{OA}$	Common mode rejection ratio	60	–	–	dB	–
G_{OLOA}	Open loop gain	80	–	–	dB	–
$V_{OHIGHOA}$	High output voltage swing (internal signals)	V_{DD} – 0.01	–	–	V	–
V_{OLOWOA}	Low output voltage swing (internal signals)	–	–	0.01	V	–
I_{SOA}	Supply current (including associated AGND buffer) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = Medium, Opamp bias = Low Power = Medium, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	 – – – – – –	 150 300 600 1200 2400 –	 200 400 800 1600 3200 –	 µA µA µA µA µA µA	Power = High, Opamp bias = High setting is not allowed for 3.3 V V_{DD} operation.
$PSRR_{OA}$	Supply voltage rejection ratio	54	80	–	dB	$V_{SS} \le V_{IN} \le (V_{DD} – 2.25)$ or $(V_{DD} – 1.25\ V) \le V_{IN} \le V_{DD}$

DC Low Power Comparator Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and -40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 10. DC Low Power Comparator Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{REFLPC}	Low power comparator (LPC) reference voltage range	0.2	–	V_{DD} - 1	V	–
I_{SLPC}	LPC supply current	–	10	40	µA	–
V_{OSLPC}	LPC voltage offset	–	2.5	30	mV	–

DC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and -40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

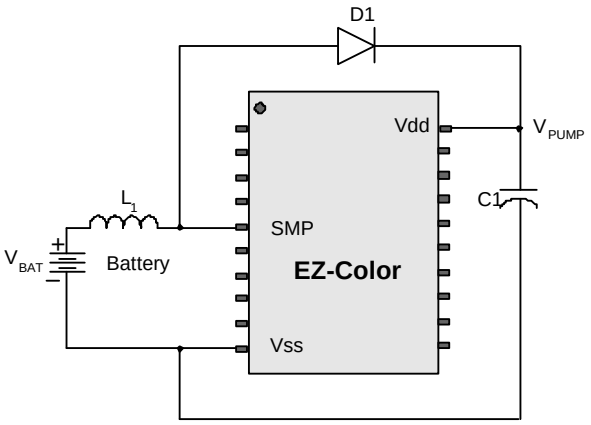
Table 11. 5-V DC Analog Output Buffer Specifications

Symbol	Description	Min	Typ	Max	Unit	Notes
V_{OSOB}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	 – – – –	 3.2 3.2 3.2 3.2	 18 18 18 18	 mV mV mV mV	–
TCV_{OSOB}	Average input offset voltage drift	–	5.5	26	µV/°C	–
V_{CMOB}	Common-mode input voltage range	0.5	–	V_{DD} – 1.0	V	–
R_{OUTOB}	Output resistance Power = Low Power = High	 – –	 – –	 1 1	 Ω Ω	–
$V_{OHIGHOB}$	High output voltage swing (Load = 32 ohms to V_{DD}/2) Power = Low Power = High	 0.5 × V_{DD} + 1.3 0.5 × V_{DD} + 1.3	 – –	 – –	 V V	–
V_{OLOWOB}	Low output voltage swing (Load = 32 ohms to V_{DD}/2) Power = Low Power = High	 – –	 – –	 0.5 × V_{DD} – 1.3 0.5 × V_{DD} – 1.3	 V V	–
I_{SOB}	Supply current including bias cell (no load) Power = Low Power = High	 – –	 1.1 2.6	 2 5	 mA mA	–
$PSRR_{OB}$	Supply voltage rejection ratio	40	64		dB	–
C_L	Load capacitance	–	–	200	pF	This specification applies to the external circuit driven by the analog output buffer.

Table 12. 3.3-V DC Analog Output Buffer Specifications

Symbol	Description	Min	Typ	Max	Unit	Notes
V_{OSOB}	Input offset voltage (absolute value) Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	 – – – –	 3.2 3.2 6 6	 20 20 25 25	 mV mV mV mV	High power setting is not recommended.
TCV_{OSOB}	Average input offset voltage drift Power = Low, Opamp bias = Low Power = Low, Opamp bias = High Power = High, Opamp bias = Low Power = High, Opamp bias = High	 – – – –	 8 8 12 12	 32 32 41 41	 µV/°C µV/°C µV/°C µV/°C	High power setting is not recommended.
V_{CMOB}	Common-mode input voltage range	0.5	–	V_{DD} – 1.0	V	–
R_{OUTOB}	Output resistance Power = Low Power = High	 – –	 – –	 10 10	 W W	–
$V_{OHIGHOB}$	High output voltage swing (Load = 32 ohms to V_{DD}/2) Power = Low Power = High	 0.5 × V_{DD} + 1.0 0.5 × V_{DD} + 1.0	 – –	 – –	 V V	–
V_{OLOWOB}	Low output voltage swing (Load = 32 ohms to V_{DD}/2) Power = Low Power = High	 – –	 – –	 0.5 × V_{DD} – 1.0 0.5 × V_{DD} – 1.0	 V V	–

Figure 6. Basic Switch Mode Pump Circuit



DC Analog Reference Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

The guaranteed specifications are measured through the analog continuous time PSoC blocks. The power levels for AGND refer to the power of the Analog Continuous Time PSoC block. The power levels for RefHi and RefLo refer to the analog reference control register. The limits stated for AGND include the offset error of the AGND buffer local to the Analog Continuous Time PSoC block. Reference control power is high.

Table 14. 5-V DC Analog Reference Specifications

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Typ	Max	Unit
0b000	RefPower = High Opamp bias = High	V_{REFHI}	Ref High	$V_{DD}/2$ + Bandgap	$V_{DD}/2$ + 1.228	$V_{DD}/2$ + 1.290	$V_{DD}/2$ + 1.352	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.078	$V_{DD}/2$ – 0.007	$V_{DD}/2$ + 0.063	V
		V_{REFLO}	Ref Low	$V_{DD}/2$ – Bandgap	$V_{DD}/2$ – 1.336	$V_{DD}/2$ – 1.295	$V_{DD}/2$ – 1.250	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref High	$V_{DD}/2$ + Bandgap	$V_{DD}/2$ + 1.224	$V_{DD}/2$ + 1.293	$V_{DD}/2$ + 1.356	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.056	$V_{DD}/2$ – 0.005	$V_{DD}/2$ + 0.043	V
		V_{REFLO}	Ref Low	$V_{DD}/2$ – Bandgap	$V_{DD}/2$ – 1.338	$V_{DD}/2$ – 1.298	$V_{DD}/2$ – 1.255	V
	RefPower = Med Opamp bias = High	V_{REFHI}	Ref High	$V_{DD}/2$ + Bandgap	$V_{DD}/2$ + 1.226	$V_{DD}/2$ + 1.293	$V_{DD}/2$ + 1.356	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.057	$V_{DD}/2$ – 0.006	$V_{DD}/2$ + 0.044	V
		V_{REFLO}	Ref Low	$V_{DD}/2$ – Bandgap	$V_{DD}/2$ – 1.337	$V_{DD}/2$ – 1.298	$V_{DD}/2$ – 1.256	V
	RefPower = Med Opamp bias = Low	V_{REFHI}	Ref High	$V_{DD}/2$ + Bandgap	$V_{DD}/2$ + 1.226	$V_{DD}/2$ + 1.294	$V_{DD}/2$ + 1.359	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.047	$V_{DD}/2$ – 0.004	$V_{DD}/2$ + 0.035	V
		V_{REFLO}	Ref Low	$V_{DD}/2$ – Bandgap	$V_{DD}/2$ – 1.338	$V_{DD}/2$ – 1.299	$V_{DD}/2$ – 1.258	V

Table 14. 5-V DC Analog Reference Specifications (continued)

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Typ	Max	Unit
0b011	RefPower = High Opamp bias = High	V_{REFHI}	Ref High	3 × Bandgap	3.788	3.891	3.986	V
		V_{AGND}	AGND	2 × Bandgap	2.500	2.604	3.699	V
		V_{REFLO}	Ref Low	Bandgap	1.257	1.306	1.359	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref High	3 × Bandgap	3.792	3.893	3.982	V
		V_{AGND}	AGND	2 × Bandgap	2.518	2.602	2.692	V
		V_{REFLO}	Ref Low	Bandgap	1.256	1.302	1.354	V
	RefPower = Med Opamp bias = High	V_{REFHI}	Ref High	3 × Bandgap	3.795	3.894	3.993	V
		V_{AGND}	AGND	2 × Bandgap	2.516	2.603	2.698	V
		V_{REFLO}	Ref Low	Bandgap	1.256	1.303	1.353	V
	RefPower = Med Opamp bias = Low	V_{REFHI}	Ref High	3 × Bandgap	3.792	3.895	3.986	V
		V_{AGND}	AGND	2 × Bandgap	2.522	2.602	2.685	V
		V_{REFLO}	Ref Low	Bandgap	1.255	1.301	1.350	V
0b100	RefPower = High Opamp bias = High	V_{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.495 – P2[6]	2.586 – P2[6]	2.657 – P2[6]	V
		V_{AGND}	AGND	2 × Bandgap	2.502	2.604	2.719	V
		V_{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.531 – P2[6]	2.611 – P2[6]	2.681 – P2[6]	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.500 – P2[6]	2.591 – P2[6]	2.662 – P2[6]	V
		V_{AGND}	AGND	2 × Bandgap	2.519	2.602	2.693	V
		V_{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.530 – P2[6]	2.605 – P2[6]	2.666 – P2[6]	V
	RefPower = Med Opamp bias = High	V_{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.503 – P2[6]	2.592 – P2[6]	2.662 – P2[6]	V
		V_{AGND}	AGND	2 × Bandgap	2.517	2.603	2.698	V
		V_{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.529 – P2[6]	2.606 – P2[6]	2.665 – P2[6]	V
	RefPower = Med Opamp bias = Low	V_{REFHI}	Ref High	2 × Bandgap + P2[6] (P2[6] = 1.3 V)	2.505 – P2[6]	2.594 – P2[6]	2.665 – P2[6]	V
		V_{AGND}	AGND	2 × Bandgap	2.525	2.602	2.685	V
		V_{REFLO}	Ref Low	2 × Bandgap – P2[6] (P2[6] = 1.3 V)	2.528 – P2[6]	2.603 – P2[6]	2.661 – P2[6]	V

Table 15. 3.3-V DC Analog Reference Specifications (continued)

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Typ	Max	Unit
0b010	RefPower = High Opamp bias = High	V_{REFHI}	Ref High	V_{DD}	V_{DD} – 0.06	V_{DD} – 0.010	V_{DD}	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.05	$V_{DD}/2$ – 0.002	$V_{DD}/2$ + 0.040	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.009	Vss + 0.056	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref High	V_{DD}	V_{DD} – 0.060	V_{DD} – 0.006	V_{DD}	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.028	$V_{DD}/2$ – 0.001	$V_{DD}/2$ + 0.025	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.005	Vss + 0.034	V
	RefPower = Med Opamp bias = High	V_{REFHI}	Ref High	V_{DD}	V_{DD} – 0.058	V_{DD} – 0.008	V_{DD}	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.037	$V_{DD}/2$ – 0.002	$V_{DD}/2$ + 0.033	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.007	Vss + 0.046	V
	RefPower = Med Opamp bias = Low	V_{REFHI}	Ref High	V_{DD}	V_{DD} – 0.057	V_{DD} – 0.006	V_{DD}	V
		V_{AGND}	AGND	$V_{DD}/2$	$V_{DD}/2$ – 0.025	$V_{DD}/2$ – 0.001	$V_{DD}/2$ + 0.022	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.004	Vss + 0.030	V
0b011	All power settings. Not allowed for 3.3 V	–	–	–	–	–	–	–
0b100	All power settings. Not allowed for 3.3 V	–	–	–	–	–	–	–
0b101	RefPower = High Opamp bias = High	V_{REFHI}	Ref High	P2[4] + BandGap ($P2[4] = V_{DD}/2$)	P2[4] + 1.213	P2[4] + 1.291	P2[4] + 1.367	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
		V_{REFLO}	Ref Low	P2[4] – BandGap ($P2[4] = V_{DD}/2$)	P2[4] – 1.333	P2[4] – 1.294	P2[4] – 1.208	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref High	P2[4] + BandGap ($P2[4] = V_{DD}/2$)	P2[4] + 1.217	P2[4] + 1.294	P2[4] + 1.368	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
		V_{REFLO}	Ref Low	P2[4] – BandGap ($P2[4] = V_{DD}/2$)	P2[4] – 1.320	P2[4] – 1.296	P2[4] – 1.261	V
	RefPower = Med Opamp bias = High	V_{REFHI}	Ref High	P2[4] + BandGap ($P2[4] = V_{DD}/2$)	P2[4] + 1.217	P2[4] + 1.294	P2[4] + 1.369	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
		V_{REFLO}	Ref Low	P2[4] – BandGap ($P2[4] = V_{DD}/2$)	P2[4] – 1.322	P2[4] – 1.297	P2[4] – 1.262	V
	RefPower = Med Opamp bias = Low	V_{REFHI}	Ref High	P2[4] + BandGap ($P2[4] = V_{DD}/2$)	P2[4] + 1.219	P2[4] + 1.295	P2[4] + 1.37	V
		V_{AGND}	AGND	P2[4]	P2[4]	P2[4]	P2[4]	V
		V_{REFLO}	Ref Low	P2[4] – BandGap ($P2[4] = V_{DD}/2$)	P2[4] – 1.324	P2[4] – 1.297	P2[4] – 1.262	V

Table 15. 3.3-V DC Analog Reference Specifications (continued)

Reference ARF_CR[5:3]	Reference Power Settings	Symbol	Reference	Description	Min	Typ	Max	Unit
0b110	RefPower = High Opamp bias = High	V_{REFHI}	Ref High	2 × BandGap	2.507	2.598	2.698	V
		V_{AGND}	AGND	BandGap	1.203	1.307	1.424	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.012	Vss + 0.067	V
	RefPower = High Opamp bias = Low	V_{REFHI}	Ref High	2 × BandGap	2.516	2.598	2.683	V
		V_{AGND}	AGND	BandGap	1.241	1.303	1.376	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.007	Vss + 0.040	V
	RefPower = Med Opamp bias = High	V_{REFHI}	Ref High	2 × BandGap	2.510	2.599	2.693	V
		V_{AGND}	AGND	BandGap	1.240	1.305	1.374	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.008	Vss + 0.048	V
	RefPower = Med Opamp bias = Low	V_{REFHI}	Ref High	2 × BandGap	2.515	2.598	2.683	V
		V_{AGND}	AGND	BandGap	1.258	1.302	1.355	V
		V_{REFLO}	Ref Low	Vss	Vss	Vss + 0.005	Vss + 0.03	V
0b111	All power settings. Not allowed for 3.3 V.	–	–	–	–	–	–	–

DC Analog PSoC Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 16. DC Analog PSoC Block Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{CT}	Resistor Unit Value (Continuous Time)	–	12.2	–	kΩ	
C_{SC}	Capacitor Unit Value (Switched Capacitor)	–	80	–	fF	

DC POR, SMP, and LVD Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 17. DC POR, SMP, and LVD Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
	V_{DD} Value for PPOR Trip (positive ramp)					
V_{PPOR0R}	PORLEV[1:0] = 00b		2.91		V	
V_{PPOR1R}	PORLEV[1:0] = 01b	–	4.39	–	V	
V_{PPOR2R}	PORLEV[1:0] = 10b		4.55		V	
	V_{DD} Value for PPOR Trip (negative ramp)					
V_{PPOR0}	PORLEV[1:0] = 00b		2.82		V	
V_{PPOR1}	PORLEV[1:0] = 01b	–	4.39	–	V	
V_{PPOR2}	PORLEV[1:0] = 10b		4.55		V	
	PPOR Hysteresis					
V_{PH0}	PORLEV[1:0] = 00b	–	92	–	mV	
V_{PH1}	PORLEV[1:0] = 01b	–	0	–	mV	
V_{PH2}	PORLEV[1:0] = 10b	–	0	–	mV	

Notes
4. Always greater than 50 mV above PPOR (PORLEV = 00) for falling supply.
5. Always greater than 50 mV above PPOR (PORLEV = 10) for falling supply.

DC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –-40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 18. DC Programming Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{DDP}	V_{DD} for programming and erase	4.5	5	5.5	V	This specification applies to the functional requirements of external programmer tools.
V_{DDLV}	Low V_{DD} for verify	3.0	3.1	3.2	V	This specification applies to the functional requirements of external programmer tools.
V_{DDHV}	High V_{DD} for verify	5.1	5.2	5.3	V	This specification applies to the functional requirements of external programmer tools.
$V_{DDIWRITE}$	Supply voltage for flash write operation	3.15	–	5.25	V	This specification applies to this device when it is executing internal flash writes.
I_{DDP}	Supply current during programming or verify	–	10	30	mA	
V_{ILP}	Input Low-voltage during programming or verify	–	–	0.8	V	
V_{IHP}	Input High-voltage during programming or verify	2.2	–	–	V	
I_{ILP}	Input Current when Applying V_{ILP} to P1[0] or P1[1] During Programming or Verify	–	–	0.2	mA	Driving internal pull-down resistor.
I_{IHP}	Input Current when Applying V_{IHP} to P1[0] or P1[1] During Programming or Verify	–	–	1.5	mA	Driving internal pull-down resistor.
V_{OLV}	Output Low-voltage during programming or verify	–	–	Vss + 0.75	V	
V_{OHV}	Output High-voltage during programming or verify	V_{DD} - 1.0	–	V_{DD}	V	
$Flash_{ENPB}$	flash endurance (per block)	50,000[6]	–	–	–	Erase/write cycles per block.
$Flash_{ENT}$	flash endurance (total)[7]	1,800,000	–	–	–	Erase/write cycles.
$Flash_{DR}$	flash data retention	10	–	–	Years	

DC I^2C Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

Table 19. DC I^2C Specifications

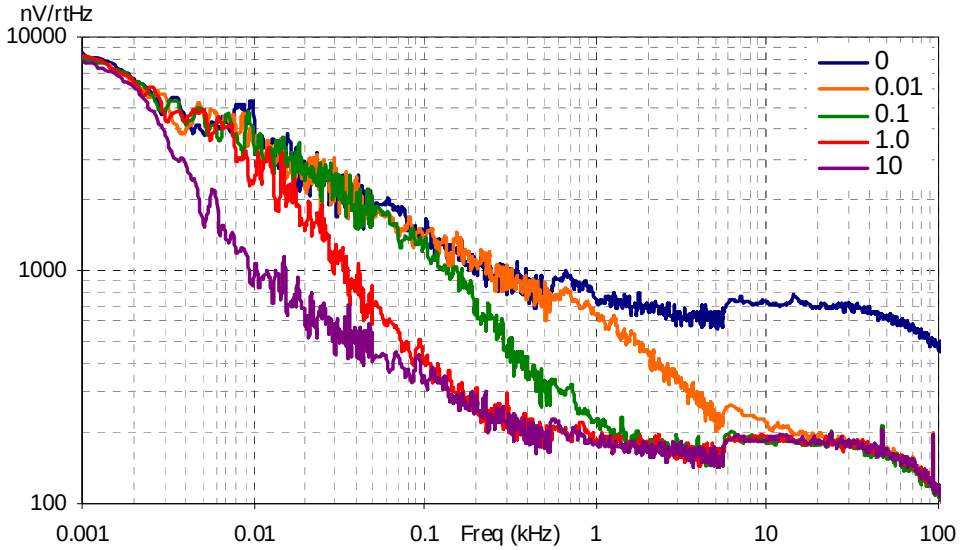
Parameter	Description	Min	Typ	Max	Units	Notes
V_{ILI2C}[8]	Input low level	–	–	0.3 × V_{DD}	V	3.0 V ≤ V_{DD} ≤ 3.6 V
		–	–	0.25 × V_{DD}	V	4.75 V ≤ V_{DD} ≤ 5.25 V
V_{IHI2C}[8]	Input high level	0.7 × V_{DD}	–	–	V	3.0 V ≤ V_{DD} ≤ 5.25 V

Notes

6. The 50,000 cycle flash endurance per block is only guaranteed if the Flash is operating within one voltage range. Voltage ranges are 3.0 V to 3.6 V and 4.75 V to 5.25 V.
7. A maximum of 36 x 50,000 block endurance cycles is allowed. This may be balanced between operations on 36x1 blocks of 50,000 maximum cycles each, 36x2 blocks of 25,000 maximum cycles each, or 36x4 blocks of 12,500 maximum cycles each (to limit the total number of cycles to 36x50,000 and that no single block ever sees more than 50,000 cycles).
   For the full industrial range, the user must employ a temperature sensor user module (flashTemp) and feed the result to the temperature argument before writing. Refer to the Flash APIs Application Note AN2015 at http://www.cypress.com under Application Notes for more information.
8. All GPIOs meet the DC GPIO V_{IL} and V_{IH} specifications found in the DC GPIO specifications sections.The I^2C GPIO pins also meet the mentioned specs.

When bypassed by a capacitor on P2[4], the noise of the analog ground signal distributed to each block is reduced by a factor of up to 5 (14 dB). This is at frequencies above the corner frequency defined by the on-chip 8.1k resistance and the external capacitor.

Figure 11. Typical AGND Noise with P2[4] Bypass



At low frequencies, the opamp noise is proportional to 1/f, power independent, and determined by device geometry. At high frequencies, increased power level reduces the noise spectrum level.

Figure 12. Typical Opamp Noise

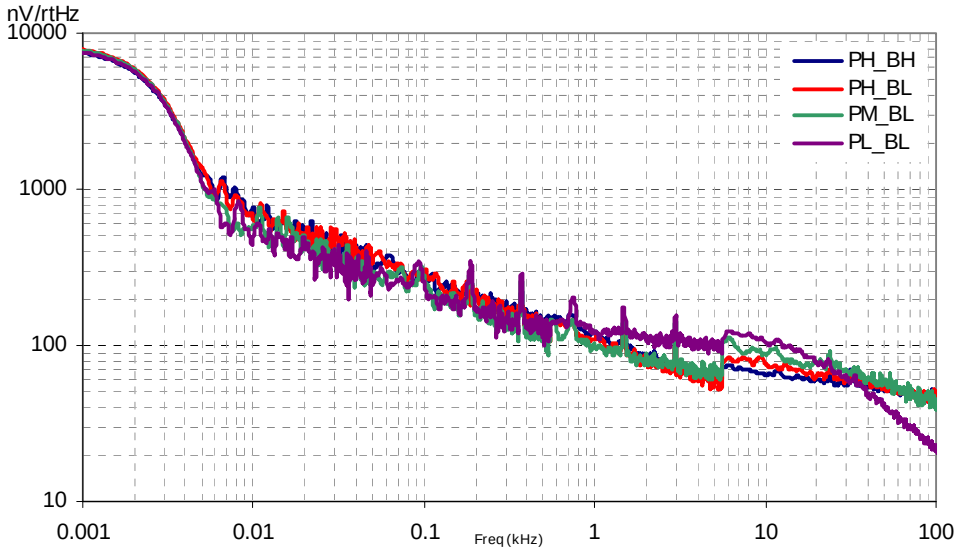


Table 27. 3.3V AC Analog Output Buffer Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
T_{ROB}	Rising Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High	 – –	 – –	 4.7 4.7	 µs µs	
T_{SOB}	Falling Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High	 – –	 – –	 4 4	 µs µs	
SR_{ROB}	Rising Slew Rate (20% to 80%), 1 V Step, 100pF Load Power = Low Power = High	 .36 .36	 – –	 – –	 V/µs V/µs	
SR_{FOB}	Falling Slew Rate (80% to 20%), 1 V Step, 100pF Load Power = Low Power = High	 .4 .4	 – –	 – –	 V/µs V/µs	
BW_{OB}	Small Signal Bandwidth, 20mV$_{pp}$, 3dB BW, 100pF Load Power = Low Power = High	 0.7 0.7	 – –	 – –	 MHz MHz	
BW_{OB}	Large Signal Bandwidth, 1V$_{pp}$, 3dB BW, 100pF Load Power = Low Power = High	 200 200	 – –	 – –	 kHz kHz	

AC External Clock Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and -40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and -40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters apply to 5 V and 3.3 V at 25 °C and are for design guidance only.

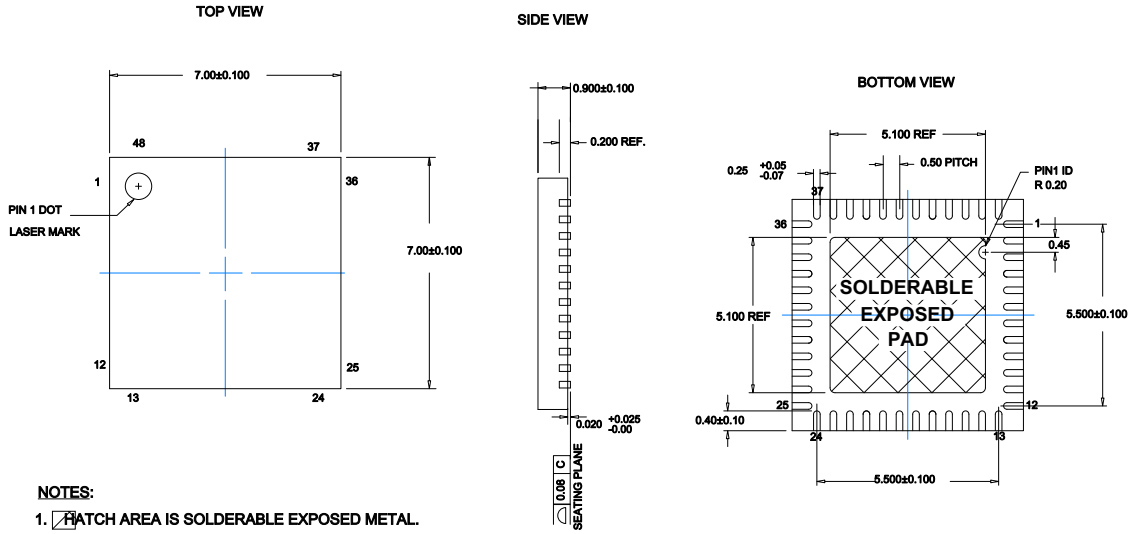
Table 28. 5V AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{OSCEXT}	Frequency	0.093	–	24.6	MHz	
–	High Period	20.6	–	5300	ns	
–	Low Period	20.6	–	–	ns	
–	Power Up IMO to Switch	150	–	–	µs	

Table 29. 3.3V AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{OSCEXT}	Frequency with CPU Clock Divide by 1	0.093	–	12.3	MHz	Maximum CPU frequency is 12 MHz at 3.3V. With the CPU clock divider set to 1, the external clock must adhere to the maximum frequency and duty cycle requirements.
F_{OSCEXT}	Frequency with CPU Clock Divide by 2 or Greater	0.186	–	24.6	MHz	If the frequency of the external clock is greater than 12 MHz, the CPU clock divider must be set to 2 or greater. In this case, the CPU clock divider will ensure that the fifty percent duty cycle requirement is met.
–	High Period with CPU Clock Divide by 1	41.7	–	5300	ns	–
–	Low Period with CPU Clock Divide by 1	41.7	–	–	ns	–
–	Power Up IMO to Switch	150	–	–	µs	–

Figure 15. 48-Pin (7 × 7 × 1.0 mm) QFN (Sawn)



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Important Note

For information on the preferred dimensions for mounting QFN packages, see the following Application Note "Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages" available at http://www.amkor.com.

Pinned vias for thermal conduction are not required for the low-power device.

Thermal Impedances

Table 32. Thermal Impedances per Package

Package	Typical θ_{JA} [17]
28 SSOP	94 °C/W
48 QFN[18]	28 °C/W

Capacitance on Crystal Pins

Table 33. Typical Package Capacitance on Crystal Pins

Package	Package Capacitance
28 SSOP	2.8 pF
48 QFN	1.8 pF

Solder Reflow Peak Temperature

Following is the minimum solder reflow peak temperature to achieve good solderability.

Table 34. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Time at Maximum Peak Temperature
28 SSOP	260 °C	30 s
48 QFN	260 °C	30 s

Notes
17. $T_J = T_A + POWER \times \theta_{JA}$
18. To achieve the thermal impedance specified for the QFN package, refer to "Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages" available at http://www.amkor.com.

Acronyms

Acronyms Used

Table 37 lists the acronyms that are used in this document.

Table 37. Acronyms Used in this Datasheet

Acronym	Description	Acronym	Description
AC	alternating current	MAC	multiply-accumulate
ADC	analog-to-digital converter	MIPS	million instructions per second
API	application programming interface	PCB	printed circuit board
CMOS	complementary metal oxide semiconductor	PDIP	plastic dual-in-line package
CPU	central processing unit	PLL	phase-locked loop
CRC	cyclic redundancy check	POR	power-on reset
CT	continuous time	PPOR	precision power on reset
DAC	digital-to-analog converter	PRS	pseudo-random sequence
DC	direct current	PSoC®	Programmable System-on-Chip
DTMF	dual-tone multi-frequency	PWM	pulse-width modulator
ECO	external crystal oscillator	QFN	quad flat no leads
EEPROM	electrically erasable programmable read-only memory	RTC	real time clock
GPIO	general purpose I/O	SAR	successive approximation
ICE	in-circuit emulator	SC	switched capacitor
IDE	integrated development environment	SMP	switch mode pump
ILO	internal low speed oscillator	SPI	serial peripheral interface
IMO	internal main oscillator	SRAM	static random access memory
I/O	input/output	SROM	supervisory read only memory
IrDA	infrared data association	SSOP	shrink small-outline package
ISSP	in-system serial programming	UART	universal asynchronous reciever / transmitter
LCD	liquid crystal display	USB	universal serial bus
LED	light-emitting diode	WDT	watchdog timer
LPC	low power comparator	XRES	external reset
LVD	low-voltage detect		

Reference Documents

Design Aids – Reading and Writing PSoC® Flash – AN2015 (001-40459)

Understanding Datasheet Jitter Specifications for Cypress Timing Products – AN5054 (001-14503)

Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages – available at http://www.amkor.com.

Document Conventions

Units of Measure

Table 38 lists the units of measures.

Table 38. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
dB	decibels	ms	milliseconds
°C	degree Celsius	mH	millihenry
fF	femtofarad	ns	nanoseconds
kHz	kilohertz	µV	microvolts
kΩ	kilohm	V	volts
MHz	megahertz	mV	millivolts
µA	microamperes	µW	microwatts
µs	microseconds	%	percent
mA	milliamperes	W	watt
nA	nanoamperes	mm	millimeters
pF	picofarad	ps	picosecond
pA	pikoamperes	ppm	parts per million
rt-Hz	root hertz	nV	nanovolts

Numeric Conventions

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase ‘h’ (for example, ‘14h’ or ‘3Ah’). Hexadecimal numbers may also be represented by a ‘0x’ prefix, the C coding convention. Binary numbers have an appended lowercase ‘b’ (for example, 01010100b’ or ‘01000011b’). Numbers not indicated by an ‘h’, ‘b’, or 0x are decimals.

Glossary

active high	1. A logic signal having its asserted state as the logic 1 state. 2. A logic signal having the logic 1 state as the higher voltage of the two states.
analog blocks	The basic programmable opamp circuits. These are switched capacitor (SC) and continuous time (CT) blocks. These blocks can be interconnected to provide ADCs, DACs, multi-pole filters, gain stages, and much more.
analog-to-digital (ADC)	A device that changes an analog signal to a digital signal of corresponding magnitude. Typically, an ADC converts a voltage to a digital number. The digital-to-analog (DAC) converter performs the reverse operation.
Application programming interface (API)	A series of software routines that comprise an interface between a computer application and lower level services and functions (for example, user modules and libraries). APIs serve as building blocks for programmers that create software applications.
asynchronous	A signal whose data is acknowledged or acted upon immediately, irrespective of any clock signal.
bandgap reference	A stable voltage reference design that matches the positive temperature coefficient of VT with the negative temperature coefficient of VBE, to produce a zero temperature coefficient (ideally) reference.
bandwidth	1. The frequency range of a message or information processing system measured in hertz. 2. The width of the spectral region over which an amplifier (or absorber) has substantial gain (or loss); it is sometimes represented more specifically as, for example, full width at half maximum.

Glossary (continued)

bias	1. A systematic deviation of a value from a reference value. 2. The amount by which the average of a set of values departs from a reference value. 3. The electrical, mechanical, magnetic, or other force (field) applied to a device to establish a reference level to operate the device.
block	1. A functional unit that performs a single function, such as an oscillator. 2. A functional unit that may be configured to perform one of several functions, such as a digital PSoC block or an analog PSoC block.
buffer	1. A storage area for data that is used to compensate for a speed difference, when transferring data from one device to another. Usually refers to an area reserved for IO operations, into which data is read, or from which data is written. 2. A portion of memory set aside to store data, often before it is sent to an external device or as it is received from an external device. 3. An amplifier used to lower the output impedance of a system.
bus	1. A named connection of nets. Bundling nets together in a bus makes it easier to route nets with similar routing patterns. 2. A set of signals performing a common function and carrying similar data. Typically represented using vector notation; for example, address[7:0]. 3. One or more conductors that serve as a common connection for a group of related devices.
clock	The device that generates a periodic signal with a fixed frequency and duty cycle. A clock is sometimes used to synchronize different logic blocks.
comparator	An electronic circuit that produces an output voltage or current whenever two input levels simultaneously satisfy predetermined amplitude requirements.
compiler	A program that translates a high level language, such as C, into machine language.
configuration space	In PSoC devices, the register space accessed when the XIO bit, in the CPU_F register, is set to ‘1’.
crystal oscillator	An oscillator in which the frequency is controlled by a piezoelectric crystal. Typically a piezoelectric crystal is less sensitive to ambient temperature than other circuit components.
cyclic redundancy check (CRC)	A calculation used to detect errors in data communications, typically performed using a linear feedback shift register. Similar calculations may be used for a variety of other purposes such as data compression.
data bus	A bi-directional set of signals used by a computer to convey information from a memory location to the central processing unit and vice versa. More generally, a set of signals used to convey data between digital functions.
debugger	A hardware and software system that allows you to analyze the operation of the system under development. A debugger usually allows the developer to step through the firmware one step at a time, set break points, and analyze memory.
dead band	A period of time when neither of two or more signals are in their active state or in transition.
digital blocks	The 8-bit logic blocks that can act as a counter, timer, serial receiver, serial transmitter, CRC generator, pseudo-random number generator, or SPI.

Glossary (continued)

digital-to-analog (DAC)	A device that changes a digital signal to an analog signal of corresponding magnitude. The analog-to-digital (ADC) converter performs the reverse operation.
duty cycle	The relationship of a clock period high time to its low time, expressed as a percent.
emulator	Duplicates (provides an emulation of) the functions of one system with a different system, so that the second system appears to behave like the first system.
External Reset (XRES)	An active high signal that is driven into the PSoC device. It causes all operation of the CPU and blocks to stop and return to a pre-defined state.
flash	An electrically programmable and erasable, non-volatile technology that provides you the programmability and data storage of EPROMs, plus in-system erasability. Non-volatile means that the data is retained when power is OFF.
flash block	The smallest amount of flash ROM space that may be programmed at one time and the smallest amount of flash space that may be protected. A flash block holds 64 bytes.
frequency	The number of cycles or events per unit of time, for a periodic function.
gain	The ratio of output current, voltage, or power to input current, voltage, or power, respectively. Gain is usually expressed in dB.
I^2C	A two-wire serial computer bus by Philips Semiconductors (now NXP Semiconductors). I^2C is an Inter-Integrated Circuit. It is used to connect low-speed peripherals in an embedded system. The original system was created in the early 1980s as a battery control interface, but it was later used as a simple internal bus system for building control electronics. I2C uses only two bi-directional pins, clock and data, both running at +5 V and pulled high with resistors. The bus operates at 100 kbits/second in standard mode and 400 kbits/second in fast mode.
ICE	The in-circuit emulator that allows you to test the project in a hardware environment, while viewing the debugging device activity in a software environment (PSoC Designer).
input/output (I/O)	A device that introduces data into or extracts data from a system.
interrupt	A suspension of a process, such as the execution of a computer program, caused by an event external to that process, and performed in such a way that the process can be resumed.
interrupt service routine (ISR)	A block of code that normal code execution is diverted to when the M8C receives a hardware interrupt. Many interrupt sources may each exist with its own priority and individual ISR code block. Each ISR code block ends with the RETI instruction, returning the device to the point in the program where it left normal program execution.
jitter	1. A misplacement of the timing of a transition from its ideal position. A typical form of corruption that occurs on serial data streams. 2. The abrupt and unwanted variations of one or more signal characteristics, such as the interval between successive pulses, the amplitude of successive cycles, or the frequency or phase of successive cycles.
low-voltage detect (LVD)	A circuit that senses V_{DD} and provides an interrupt to the system when V_{DD} falls lower than a selected threshold.
M8C	An 8-bit Harvard-architecture microprocessor. The microprocessor coordinates all activity inside a PSoC by interfacing to the flash, SRAM, and register space.